#### 4.8mm BI-LEVEL LED INDICATOR

Part Number: WP73EB/2YDA Yellow

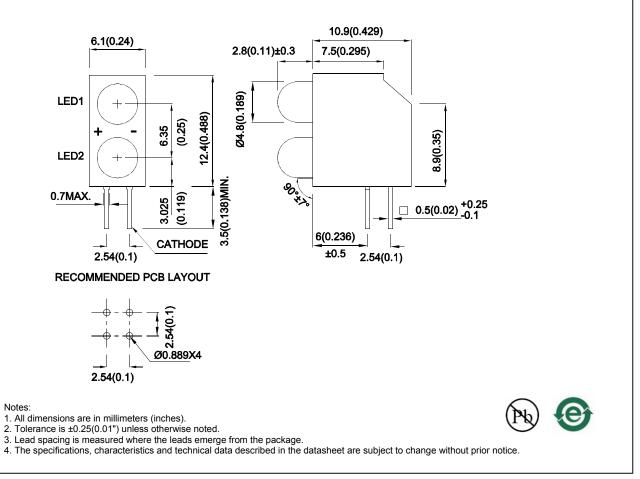
#### Features

- Pre-trimmed leads for pc board mounting.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

#### Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

#### Package Dimensions



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#### Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]	
			Min.	Тур.	201/2	
WP73EB/2YDA	Yellow (GaAsP/GaP)	Yellow Diffused	6	15	60°	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=10mA
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=10mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=10mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	1.95	2.5	V	I⊧=10mA
IR	Reverse Current	Yellow		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

 Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

#### Absolute Maximum Ratings at TA=25°C

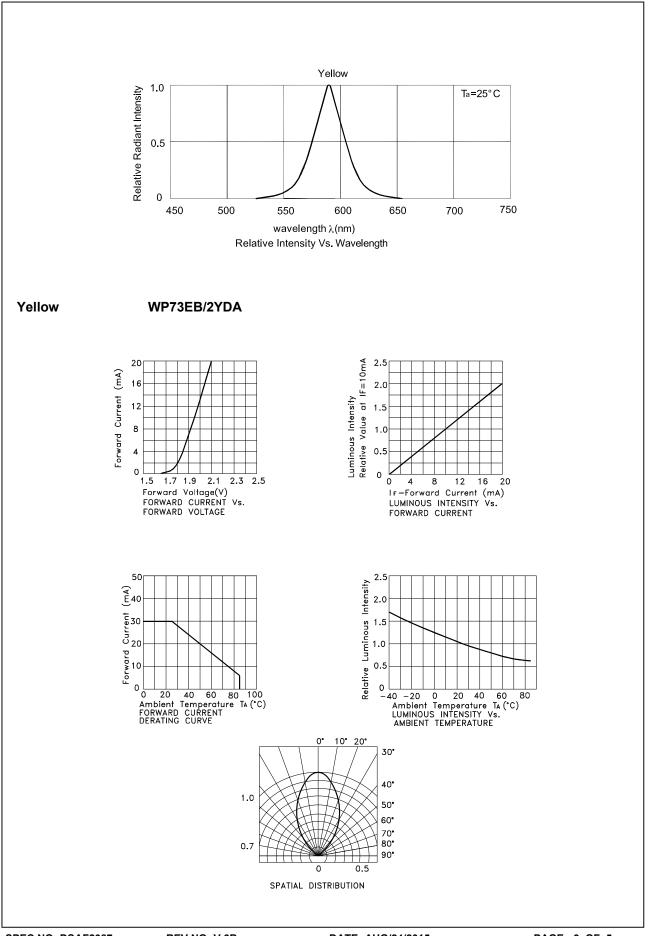
Parameter	Values	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

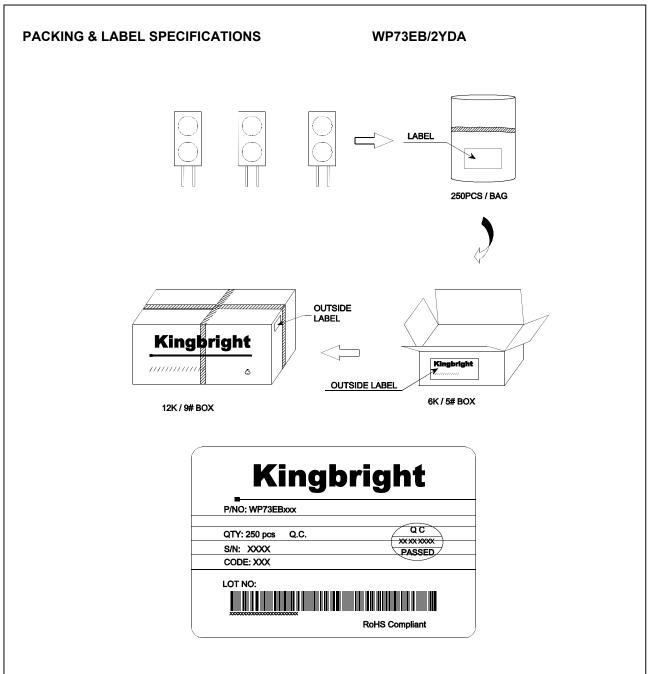
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.





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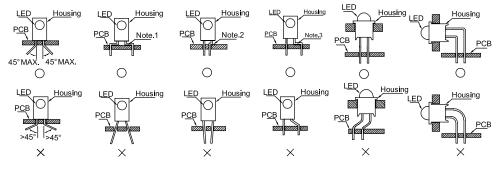
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#### PRECAUTIONS

1. Storage conditions:

a.Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.

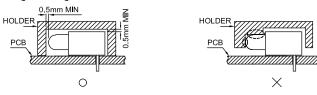
- b.LEDs should be stored with temperature  $\leq 30^{\circ}$  C and relative humidity < 60%.
- c.Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.
- 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



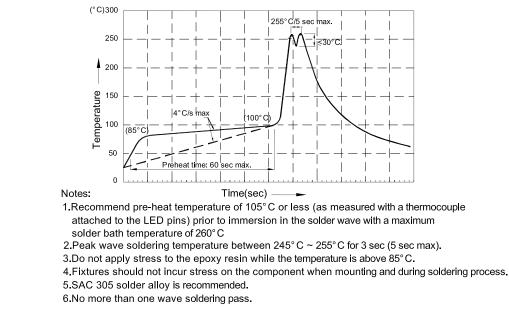
" ( ) " Correct mounting method " imes " Incorrect mounting method

Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- 4. The tip of the soldering iron should never touch the lens epoxy.
- 5. Through-hole LEDs are incompatible with reflow soldering.
- 6. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.
- 7. Recommended Wave Soldering Profiles:



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